



Transition Schedule for Additional Wafer Fabrication Site for 28nm Product Families

XTP262 (v1.1) February 24, 2014

Overview

To ensure business continuity and enable high volume supply chain capabilities for 28nm product families, Xilinx intends to qualify an additional wafer Fabrication site, TSMC SMP/Fab15. Xilinx and TSMC are partnering to create a seamless synchronized process across wafer Fabrication sites for the 28nm node with standardized HPL process manufacturing control systems. This applies to all Artix®-7, Kintex®-7, Virtex®-7, and Zynq®-7000 (XC) Commercial (C), Extended (E), and Industrial (I) grade products. Automotive (XA) and Hi-Rel (XQ) 28nm products are not impacted by this change as they will be qualified and released to production in TSMC SMP/Fab15 only.

This addition will adhere to the same performance, quality and reliability specifications that apply to all 28nm product families proven through characterization and testing. As a result, there is no change in form, fit, function, or reliability with this SMP/Fab15 addition (Refer to [XCN14004](#)).

Products affected

The affected devices are listed in [Table 1](#). This includes all packages for the affected devices. The changes also apply to all Specification Control Devices (SCD) of these affected product families.

Table 1: Affected Standard 28nm Product Families

Device	Device	Device	Device	Device
XC7A100T	XC7K355T	XC7V2000T	XC7VX485T	XC7Z010
XC7A200T	XC7K410T	XC7VH580T	XC7VX550T	XC7Z020
XC7K70T	XC7K420T	XC7VH870T	XC7VX690T	XC7Z030
XC7K160T	XC7K480T	XC7VX330T	XC7VX980T	XC7Z045
XC7K325T	XC7V585T	XC7VX415T	XC7VX1140T	XC7Z100

Transition Schedule

Xilinx will start shipping 28nm product families from TSMC SMP/Fab 15 with the timelines indicated in [Table 2](#) below. Xilinx will continue to cross ship TSMC Fab 12 material as needed for optimal supply.

Table 2: Fab 15 Device Qualification Completion and Transition Schedule

Device	Qualification Completion	Cross-Ship Date
XC7A100T	Dec-13	Apr-14
XC7A200T	Apr-14	Jul-14
XC7K70T	Jun-14	Sep-14
XC7K160T	May-14	Aug-14
XC7K325T	Dec-13	Apr-14
XC7K355T	Jun-14	Sep-14
XC7K410T	Jun-14	Sep-14
XC7K420T	May-14	Aug-14
XC7K480T	May-14	Aug-14

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Table 2 (Continued): Fab 15 Device Qualification Completion and Transition Schedule

Device	Qualification Completion	Cross-Ship Date
XC7V585T	Jul-14	Oct-14
XC7V2000T	Jun-14	Sep-14
XC7VH580T	Jul-14	Oct-14
XC7VH870T	Jul-14	Oct-14
XC7VX330T	Jul-14	Oct-14
XC7VX415T	Jun-14	Sep-14
XC7VX485T	Jan-14	Jul-14
XC7VX550T	Feb-14	May-14
XC7VX690T	Feb-14	July-14
XC7VX980T	Jun-14	Sep-14
XC7VX1140T	Jul-14	Oct-14
XC7Z010	Dec-13	Apr-14
XC7Z020	Dec-13	Apr-14
XC7Z030	Mar-14	Jun-14
XC7Z045	Mar-14	Jun-14
XC7Z100	Apr-14	Jul-14

Note: Schedule changes will not be updated in the PCN document [XCN14004](#). Any schedule changes will be updated in [Table 2](#) of this document only.

Revision History

The following table shows the revision history for this document:

Date	Version	Description of Revisions
12/16/2013	1.0	Initial release.
02/24/2014	1.1	(Table 2) update XC7VX690T cross-ship date from TBD to July, 2014.

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